

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	(laser near (micro or submicron)) and ((hole or via or holes or vias) near (drill or drilled or drilling)) and (translation near stage) and (demagnifier) and (optical near path)	USOCR	OR	ON	2005/08/11 17:01
L2	1	(laser near (micro or submicron)) and ((hole or via or holes or vias) near (drill or drilled or drilling)) and (translation near stage) and (demagnifier) and (optical near path)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:01
L3	1	(laser near (micro or submicron)) and ((hole or via or holes or vias) near (drill or drilled or drilling)) and (translation near stage) and (demagnifier)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:01
L4	1	(laser near (micro or submicron)) and (translation near stage) and (demagnifier) and (optical near path)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:02
L5	1	(laser near (micro or submicron)) and (translation same stage) and (demagnifier) and (optical near path)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:02
L6	5	laser and (micro or submicron) and (translation same stage) and (demagnifier) and (optical near path)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:03
L7	1	laser and (micro or submicron) and (translation same stage) and (demagnifier) and (optical near path) and drilling	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:02
L8	6	laser and (micro or submicron) and stage and (demagnifier) and (optical near path)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:03
L9	1	laser and ((drilling or ablation or drilled or drill or ablate) near (hole or via or holes or vias)) and (micro or submicron) and stage and (demagnifier)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:04
L10	867	laser and ((drilling or ablation or drilled or drill or ablate) near (hole or via or holes or vias)) and (micro or submicron) and stage	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:05

L11	64	laser and ((drilling or ablation or drilled or drill or ablate) near (hole or via or holes or vias)) and (micro or submicron) and (translation near stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:05
L12	15	laser and ((drilling or ablation or drilled or drill or ablate) near (hole or via or holes or vias)) and ((machine or machining) near (micro or submicron)) and (translation near stage)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2005/08/11 17:05